

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Kazuhiro OTSU et al. :
Serial No. [NEW] : **Attn: Application Branch**
Filed February 7, 2002 : **Attorney Docket No. 2002-0208A**

SEPARATING MACHINE FOR THINNED :
SEMICONDUCTOR SUBSTRATE AND :
SEPARATION METHOD :

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

In the interest of compact prosecution and to reduce PTO filing fees, please amend the present application as follows:

IN THE CLAIMS:

Please rewrite claim 4 as follows:

4. (Amended) A separating machine for a thinned semiconductor substrate according to claim 2, wherein the system for making a starting point for the separation is a system of pressing with a knife edge.

Please add the following new claim:

9. (New) A separating machine for a thinned semiconductor substrate according to claim 3, wherein the system for making a starting point for the separation is a system of pressing with a knife edge.

REMARKS


The above amendment is presented to eliminate multiple dependent claims, thereby reducing PTO filing fees.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is entitled "**Version with Markings to Show Changes Made**".

Favorable action on the merits is now requested.

Respectfully submitted,

Kazuhiro OTSU et al.

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February 7, 2002

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Please rewrite claim 4 as follows:

4. (Amended) A separating machine for a thinned semiconductor substrate according to claim 2 [or 3], wherein the system for making a starting point for the separation is a system of pressing with a knife edge.

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